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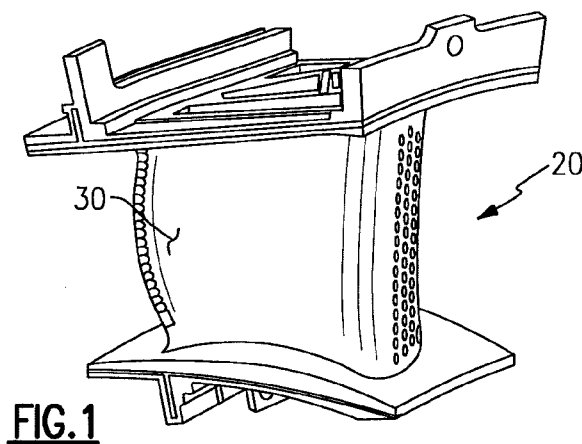
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(54) Title: WIDE GAP BRAZE



(57) Abstract: A method to fill a gap in a component according to one disclosed non-limiting embodiment of the present disclosure includes applying an alloy powder onto the component such that the alloy powder is received into a gap in response to vibrating of the component.